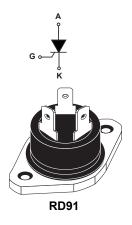


50 A,1000 V SCR thyristor in RD91



Features

- · High current SCR
- · High commutation capability
- · Low thermal resistance with clip bonding
- Insulated package RD91 high power:
 - Low thermal resistance with clip bonding
 - Insulated voltage: 2500 V_{RMS}
 - Complies with UL 1557 (File ref : E81734)
- RoHS (2002/95/EC) compliant

Applications

- Solid state relays
- · Welding equipment
- · High power motor control

Description

lectronics sales office

Available in 2500 V insulated high power package, the 50 A and 1000 V SCR BTW67 is suitable in applications where power handling and power dissipation are critical, such as solid state relays, welding equipment and high power motor control.

Based on a clip assembly technology, they offer a superior performance in surge current handling capabilities.

Product status link
BTW67

Product summary		
I _{T(RMS)}	50 A	
V _{DRM} /V _{RRM}	1000 V	
I _{GT}	80 mA	



1 Characteristics

Table 1. Absolute maximum ratings

Symbol	Parameters				Unit
I _{T(RMS)}	RMS on-state current (full sine wave)		T _c = 70 °C	50	Α
IT _(AV)	Average on-state current (180° conduction angle) $T_{c} = 70 ^{\circ}\text{C}$		32	А	
I _{TSM}	Non repetitive surge peak on-state current (full cycle,	T _j initial = 25 °C)	t _p =8.3 ms	610	Α
I ² t	l^2t value for fusing $t_p = 10 \text{ ms}$		'	1680	A ² s
dl/dt	Critical rate of rise of on-state current $I_G = 2 \times I_{GT}$, $t_r \le 100 \text{ ns}$	F = 60 Hz	T _j = 125 °C	50	A/µs
I _{GM}	Peak gate current	t _p = 20 μs	T _j = 125 °C	8	Α
P _{G(AV)}	Average gate power dissipation $T_j = 125 ^{\circ}\text{C}$				W
T _{stg}	Storage junction temperature range			-40 to +150	°C
Tj	Operating junction temperature range			-40 to +125	°C
V _{GRM}	Maximum peak reverse gate voltage			5	V
V _{ins}	Insulation RMS voltage, 1 minute			2500	V

Table 2. Electrical characteristics ($T_j = 25$ °C, unless otherwise specified)

Symbol	Test conditions	Tj		Value	Unit
			Min.	8	mA
I _{GT}	$V_D = 12 \text{ V}, R_L = 33 \Omega$	25 °C	Max	80	IIIA
V _{GT}			Max	1.3	V
$V_{\sf GD}$	$V_D = V_{DRM}$, $R_L = 3.3 \text{ k}\Omega$	125 °C	Min.	0.2	V
I _H	I _H I _T = 500 mA, gate open				mA
IL	I _G = 1.2 x I _{GT}	Max.	200	mA	
dV/dt	V _D = 67 %, V _{DRM} gate open	125 °C	Min.	1000	V/µs
V _{TM}	I _{TM} = 100 A, _{tp} = 380 μs	25 °C	Max.	1.9	V
V _{TO}	threshold on-state voltage	125 °C	Max.	1.0	V
R _D	Dynamic resistance	125 °C	Max.	8.5	mΩ
1/1	$V_D = V_{DRM}$, $V_R = V_{RRM}$	25 °C	May	10	μA
I _{DRM} /I _{RRM}	VD - VDRM, VR - VRRM	125 °C	Max.	5	mA

Table 3. Thermal resistance

Symbol	Parameters Value		Unit	
R _{th(j-c)}	Junction to case (D.C)	1.0	°C/W	

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20

15

10

5

0

1.1 Characteristics curves

P(W)

55

α = 180°

45

40

35

30

25

Figure 1. Maximum average power dissipation versus

Figure 2. Average on-state current versus case temperature $I_{T(AV)}(A)$ 60 ĎС 50 40 _α = 180° 30 20 360° 10 T_C(°C) 25 50 75 100 0 125

Figure 3. Relative variation of thermal impedance versus pulse duration

 $I_{T(AV)}(A)$

20

30

40

10

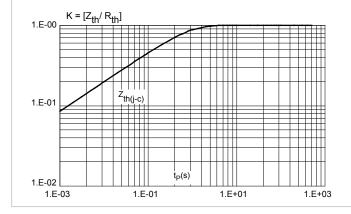


Figure 4. Relative variation of gate trigger current, holding current and latching current versus junction temperature

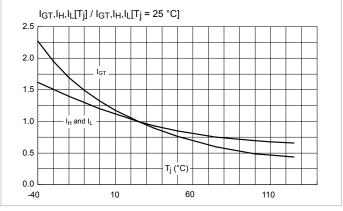


Figure 5. Surge peak on-state current versus number of cycles

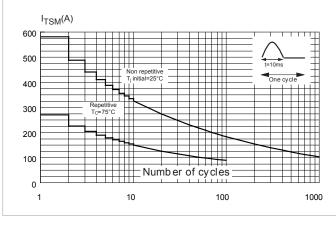
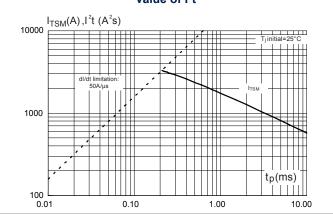


Figure 6. Non repetitive surge peak on-state current for a sinusoidal pulse with width t_p <10ms, and corresponding value of l^2t

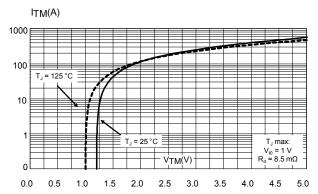


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Figure 7. On-state characteristics (maximum values)





2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

2.1 RD91 package information

- Epoxy meets UL94, V0
- Cooling method: Conduction
- Recommended torque: 0.9 to 1.2 N·m

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Α

Figure 8. RD91 package outline

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E3



Table 4. RD91 mechanical data

	Dimensions					
Ref.	mm			Inches ⁽¹⁾		
	Min.	Тур.	Max.	Min.	Тур.	Max.
Α			40.00			1.575
A1	30.10		30.30	1.185		1.193
A2			22.00			0.867
В			27.00			1.063
B1	13.50		16.50	0.531		0.650
B2			24.00			0.945
С			14.00			0.552
C1			3.50			0.138
C2	1.90		2.10	0.074		0.083
E	6.10		6.50	0.240		0.256
E2	4.80		5.20	0.188		0.205
E3	0.70		0.90	0.027		0.036
F	4.00		4.30	0.157		0.170
I	11.20		11.60	0.440		0.536
L1	3.10		3.50	0.122		0.138
L2	1.70		1.90	0.066		0.075
N1	33°		43°	33°		43°
N2	28°		38°	28°		38°

^{1.} Inches given for reference only

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3 Ordering information

Figure 9. Ordering information scheme

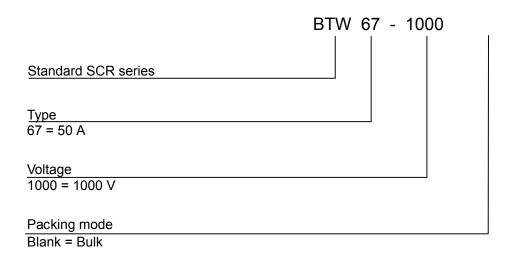


Table 5. Ordering information

Order code	Marking	Package	Weight	Base qty.	Delivery mode
BTW67-1000	BTW671000	RD91	20 g	25	Bulk

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Revision history

Table 6. Document revision history

Date	Revision	Changes
Apr-2001	4A	Last update.
13-Feb-2006	5	TOP3 Insulated delivery mode changed from bulk to tube. ECOPACK statement added.
26-Jun-2019	6	Removed TOP3 Ins. package information. Minor text changed.



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